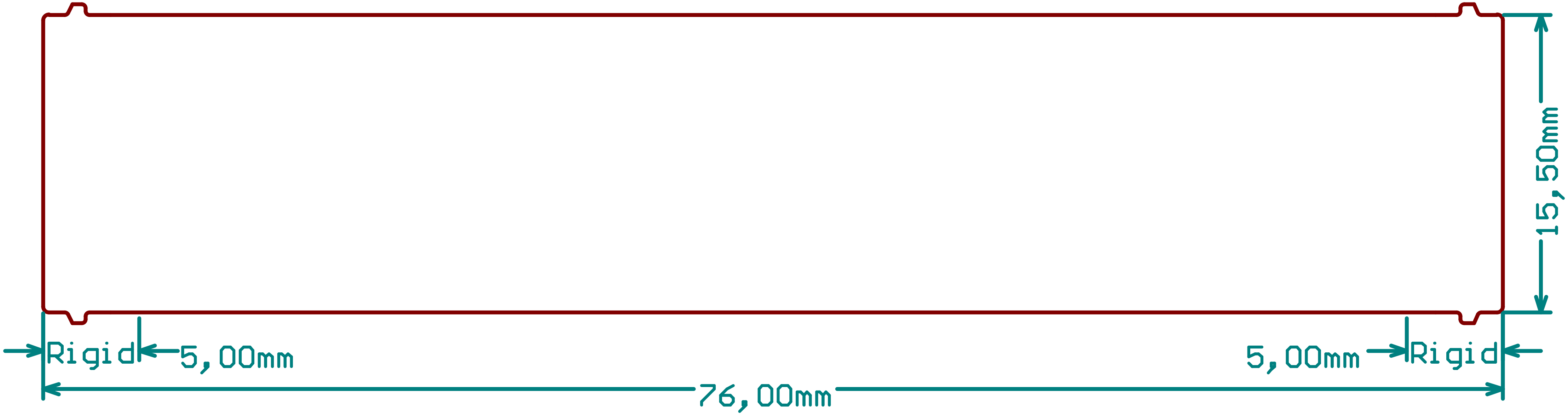

Rigid
5,00mm
5,00mm
Rigid
76,00mm
15,50mm

DOH - AB L3&L4 Flex Cable v1.1.3 - 2-layer Flex-Rigid Board

Material Selection

Polyimide
Permittivity @ 100MHz:
Permittivity @ 1GHz:
Loss Tangent @ 100MHz:
Loss Tangent @ 1GHz:
Lead Free Assembly Compatible

Solder resist colour: green
Silkscreen print colour: white

Surface Finish

On top and bottom layer surfaces:
electroless nickel immersion gold

Holes / Drilling

Drill files contain finished hole diameters
Drilling layer pairs: 1-2

Board Outline

Contour routed with break-away tabs

Element Counts

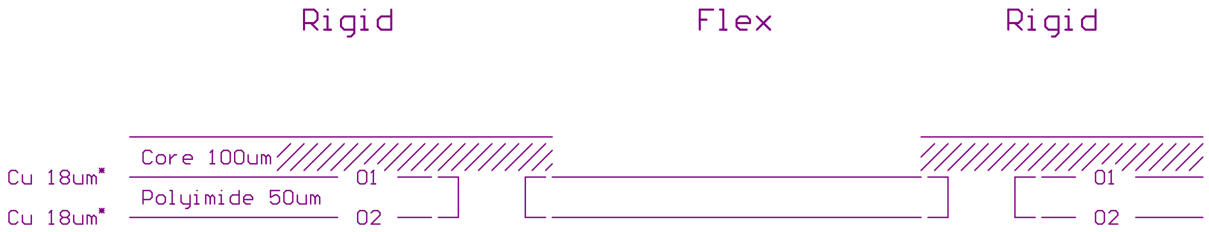
(for reference only)

Nets:	15
Pads:	60
Tracks:	252
Polygons:	0
Holes:	15
Vias:	15

Non-standard Tolerances

Holes sized 0.2mm may be plugged by plating. These are all vias.
For them we do not care the finished hole sizes.

Board Layer Stack / Drill Layer-Pairs



Layer Name	Gerber
Top Overlay	.gto
Top Solder Mask	.gts
GND	.g1
Signal Layer	.gbl
Bottom Solder Mask	.gbs
Bottom Overlay	.gbo
Board Outline	.gm1

*35um final after plating

Total Laminated Thickness on Rigid Region: 0.3mm +/- 0.05mm !

Controlled Impedance Reference

Diff. trace width/space on bottom layer (microstrip) 75 ohms +/- 10% : 0.1/0.1mm